





**QMS SERIES** 

## **RUGGED GROUND PLANE HEADER**

### **SPECIFICATIONS**

(0,635 mm) .025"

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material: Liquid Crystal Polymer Terminal & Ground Plane Material: Phosphor Bronze

Plating: Au over 50μ" (1,27 μm) Ni (Tin on Ground Plane Tail) Current Rating: Contact: 2.6 A per pin

2.6 A per pin
(1 pin powered per row)
Ground Plane:
15.7 A per ground plane
(1 ground plane powered) Voltage Rating: 300 VAC mated with QFS

Operating Temp: -55°C to +125°C RoHS Compliant: Yes

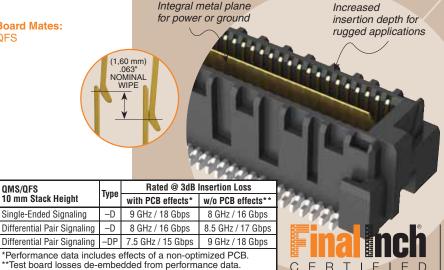
Processing: Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (026-052) (0,15 mm) .006" max (078)

**Board Stacking:** For applications requiring more than two connectors per board, contact ipg@samtec.com

### **Board Mates:**

QMS/QFS

 $\mathsf{QMS}$ 

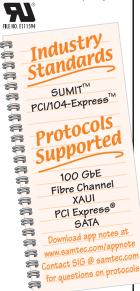


# ALSO AVAILABLE (MOQ Required)

- Other platings
- Guide Posts
- Without PCB Alignment Pins (05.75 and 06.75 only)
- Hot Pluggable
- 64 (-DP) and 104 positions per row Contact Samtec.

#### **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



Note: Some lengths, styles and options are non-standard, non-returnable.

### PINS PER ROW NO. OF PAIRS

**LEAD** STYLE

**PLATING OPTION** 

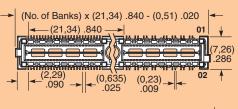
**OTHER OPTION** 

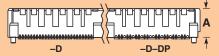
-026, -052, -078 (52 total pins per bank = -D)

Performance data for other stack heights and complete test data available at www.samtec.com?QMS or contact sig@samtec.com

-016, -032, -048 (16 pairs per bank = -D-DP)

MATED HEIGHT*						
LEAD STYLE	Α	QFS LEAD STYLE				
		-04.25	-06.25			
-05.75	(5,38) .212	10 mm	12 mm			
-06.75	(6,35) .250	11 mm	13 mm			
-09.75	(9,35) .368	14 mm	16 mm			
*Processing conditions will affect mated height.						





Specify LEAD **STYLE** from chart

-05.75 and -06.75 lead style only) = 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

(–09.75 lead style only) = 10μ" (0,25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

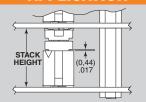


-D = Single-Ended

–D–DP = Differential Pair

-K (5,50 mm) .217" DIA Polyimide film Pick & Place Pad

### APPLICATION



Requires Standoff SO-1524-03-01-01-L for 15,24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY	INTERCONNECTS				
STANDARD	TERMINAL	SOCKET	BANKS	STACK HEIGHT	
SUMIT™	ASP-129637-01	ASP-129646-01	1	15,24 mm	
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15,24 mm	
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm	
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm	

Due to technical progress, all designs, specifications and components are subject to change without notice.

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